



Product Change Notification

Change Notification #: 118884-00
Change Title: 2.5 inch Tool Less Hot-Swap Drive Carrier
FXX25HSCAR3,
PCN 118884-00, Product Design,
Gasket implementation in 2.5" Tool-less
carrier
Date of Publication: January 27, 2022

Key Characteristics of the Change:

Product Design

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material*	February 19, 2022
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* Intel appreciates the customer's desire to receive the latest revision of products. However, Intel manages inventory on a first in first out (FIFO) basis at the MM# level. Subsequently, customer requests for a specific revision of material (below the MM#) will not be supported by Intel.

Description of Change to the Customer:

Intel is implementing the following change on the items listed in the "Products Affected" table.

- A gasket has been added on each side of the 2.5" tool less carrier (TLC), improving the flow of electricity.



Customer Impact of Change and Recommended Action:

Intel anticipates no impact to customers.

Please contact your local Intel Field Sales Representative if you have any further questions about these changes.

Products Affected/Intel Ordering Codes:

Marketing Name	Product Code	MM#	Pre Change TA	Post Change TA
2.5 inch Tool Less Hot-Swap Drive Carrier FXX25HSCAR3	FXX25HSCAR3	958244	J37327-002	J37327-003

PCN Revision History:

Date of Revision:

January 27, 2022

Revision Number:

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Reason:

Originally Published PCN



Product Change Notification

118884-00

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

Americas Contact: asmo.pcn@intel.com

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